Lead Free Solder Paste



# LEAD FREE SOLDER PASTE

# AZ Optimized for solderability

Performing with excellent heat resistance and solderability. Effective in reducing defects like unmelted BGA.

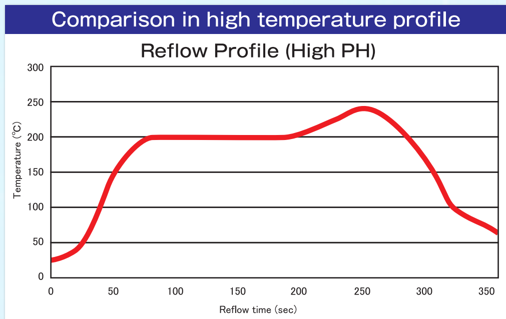
# Fine Solder

## Product Features

### Excellent heat resistance and solderability

Performing with excellent heat resistance and outstanding solderability by expanding solder paste activation temperature range based on our unique activation agent technology.

Comparison in high temperature profile

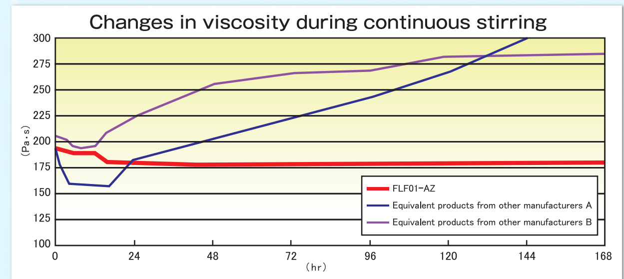


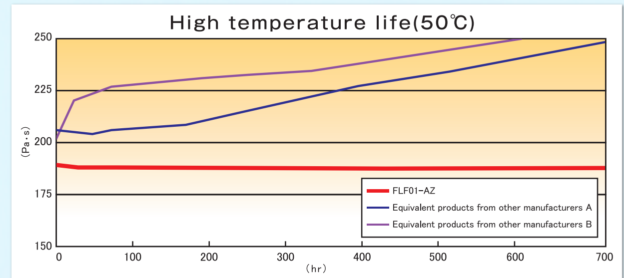
FLF01-AZ

Equivalent products from other manufacturers

### Excellent storage stability

Made with extremely stable active ingredients, excellent in stencil life and storage life at room temperatures.




| Items | FLF01-AZ | Test method |
|---|---|---|
| Alloy composition | Sn96.5%-Ag3.0%-Cu0.5% | JIS Z3282 |
| Solidus temperature | Approx. 217℃ | JIS Z3282 |
| Liquidus temperature | Approx. 219℃ | JIS Z3282 |
| Particle size | 20~38$\mu$m(Type4) | JIS Z3284(J-STD-005) |
| Flux content | 11.50% | JIS Z3197 |
| Halide content | 0.00% | JIS Z3197 |
| Viscosity | 190Pa·s | JIS Z3284 |
| Thixotropy index | 0.56 | JIS Z3284 |
| Copper plate corrosion test | Pass | JIS Z3197 |
| Insulation resistance test (85℃ 85%RH 168hr) | > $1.0\times10^9\Omega$ | JIS Z3197 |
| Migration test (85℃ 85%RH 1,000hr) | Pass | JIS Z3197 |
| Spread rate | 88% | JIS Z3197 |

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Content may be changed without notice.